

Low Pressure Chemical Vapor Deposition Vacuum Furnace

Tel: 886-3-5590169

www.syskey.com.tw



The SYSKEY Technology of vacuum system is designed for research, development and pre-production application in all branches of science and industry. Our company offers many years of experience and expertise in vacuum technology, so that we can provide you with a fully tailored system for your specific requirements

Agent at China Mainland:
www.hightrendtech.com

Email: info@syskey.com.tw
<http://www.syskey.com.tw>



Low Pressure Chemical Vapor Deposition

APPLICATIONS

The Low Pressure Chemical Vapor Deposition (LPCVD) is used for thin-film preparation, especially for Silicon, Silica, oxides, semiconductor and ceramic. Our LPCVD system is designed for R&D, development and pre-production application in all branches of science.

Applications:

- LPCVD
- Annealing
- Diffusion
- Oxidation

OUR SYSTEMS





Low Pressure Chemical Vapor Deposition

Features Specification



Chamber Size	3 ~10 inch
Chamber Material	Quartz, Al ₂ O ₃ , with water cooled stainless steel flanges
Furnace Type	Vertical or Horizontal
Temperature	Digital PID temperature controller, 1 or 3 zone
Max. Temperature	1100 °C, 1300 °C, 1500 °C, 1700 °C
Reaction Gas	O ₂ , N ₂ , H ₂ , Ar up to 6 gas line
Vacuum pump	Oil Pump, Dry Pump, Molecular Pump(Optional)
Pressure	Auto Pressure Controller(Optional)
System Control	Manual, PC, PLC